Rambus to Present at Deutsche Bank Securities, Inc. Semiconductor & Semi Capital Equipment Conference

LOS ALTOS, Calif.--May 8, 2003--Rambus Inc. (Nasdaq:RMBS), a leading provider of chip-to-chip interface products and services, will present at the Deutsche Bank Securities, Inc. Semiconductor & Semi Capital Equipment Conference on May 14, 2003 at 11:00 a.m. Pacific Time.

This event will be available through a webcast and can be accessed at Rambus' Investor Relations web site at www.rambus.com. The presentation will be available on Rambus' IR web site for one week following the event.

About Rambus Inc.

Rambus is a leading provider of chip-to-chip interface products and services. The company's breakthrough technology and engineering expertise have helped leading chip and system companies to solve their challenging I/O problems and bring industry-leading products to market. Rambus' interface solutions can be found in numerous computing, consumer electronic and networking products. Additional information is available at www.rambus.com.

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